

July 1994

## Ultra Low Noise, Precision Operational Amplifier

### Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- High Slew Rate .....  $7V/\mu s$  (Min)
- Unity Gain Bandwidth ..... 5MHz (Min)
- Low Noise Voltage (at 1kHz) .....  $4.5nV/\sqrt{Hz}$  (Max)
- Low Offset Voltage .....  $100\mu V$  (Max)
- Low Offset Drift With Temperature .....  $1.8\mu V/^{\circ}C$  (Max)
- High CMRR ..... 100dB (Min)
- High Voltage Gain ..... 700kV/V (Min)

### Applications

- High Speed Signal Conditioners
- Wide Bandwidth Instrumentation Amplifiers
- Low Level Transducer Amplifiers
- Fast, Low Level Voltage Comparators
- Highest Quality Audio Preamplifiers
- Pulse/RF Amplifiers

The HA-5127/883 monolithic operational amplifier features an excellent combination of precision DC and wideband high speed characteristics. Utilizing the Harris D.I. technology and advanced processing techniques, this unique design unites low noise precision instrumentation performance with high speed, wideband capability.

This amplifier's impressive list of features include low  $V_{OS}$ , wide gain-bandwidth, high open loop gain, and high CMRR. Additionally, this flexible device operates over a wide supply range while consuming only 120mW of power.

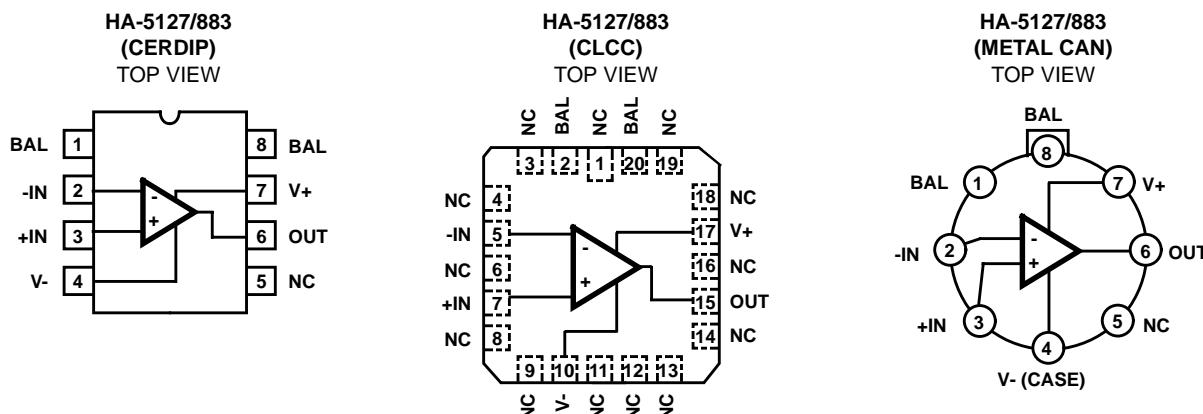
Using the HA-5127/883 allows designers to minimize errors while maximizing speed and bandwidth.

This device is ideally suited for low level transducer signal amplifier circuits. Other applications which can utilize the HA-5127/883's qualities include instrumentation amplifiers, pulse or RF amplifiers, audio preamplifiers, and signal conditioning circuits.

### Ordering Information

PART NUMBER	TEMPERATURE RANGE	PACKAGE
HA2-5127/883	-55°C to +125°C	8 Pin Can
HA4-5127/883	-55°C to +125°C	20 Lead Ceramic LCC
HA7-5127/883	-55°C to +125°C	8 Lead CerDIP

### Pinouts



# Specifications HA-5127/883

## Absolute Maximum Ratings

Voltage Between V+ and V- Terminals . . . . .	44V
Differential Input Voltage (Note 2) . . . . .	0.7V
Voltage at Either Input Terminal . . . . .	V+ to V-
Input Current. . . . .	25mA
Differential Output Current . . . . .	Full Short Circuit Protection
Junction Temperature ( $T_J$ ) . . . . .	+175°C
Storage Temperature Range . . . . .	-65°C to +150°C
ESD Rating. . . . .	<2000V
Lead Temperature (Soldering 10s). . . . .	+300°C

## Thermal Information

	$\theta_{JA}$	$\theta_{JC}$
CerDIP Package . . . . .	115°C/W	28°C/W
Ceramic LCC Package . . . . .	65°C/W	15°C/W
Metal Can Package. . . . .	155°C/W	67°C/W
Package Power Dissipation Limit at $+75^{\circ}\text{C}$ for $T_J \leq +175^{\circ}\text{C}$		
CerDIP Package . . . . .	870mW	
Ceramic LCC Package . . . . .		1.54W
Metal Can Package. . . . .		645mW
Package Power Dissipation Derating Factor Above $+75^{\circ}\text{C}$		
CerDIP Package . . . . .	8.7mW/ $^{\circ}\text{C}$	
Ceramic LCC Package . . . . .		15.4mW/ $^{\circ}\text{C}$
Metal Can Package. . . . .		6.5mW/ $^{\circ}\text{C}$

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

## Recommended Operating Conditions

Operating Temperature Range . . . . .	-55°C to +125°C	$V_{INCM} \leq 1/2 (V+ - V-)$
Operating Supply Voltage. . . . .	$\pm 15\text{V}$	$R_L \geq 600\Omega$

**TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS**

Device Tested at:  $V_{SUPPLY} = \pm 15\text{V}$ ,  $R_{SOURCE} = 50\Omega$ ,  $R_{LOAD} = 100\text{k}\Omega$ ,  $V_{OUT} = 0\text{V}$ , Unless Otherwise Specified.

PARAMETERS	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Input Offset Voltage	$V_{IO}$	$V_{CM} = 0\text{V}$	1	+25°C	-100	100	$\mu\text{V}$
			2, 3	+125°C, -55°C	-300	300	$\mu\text{V}$
Input Bias Current	$I_B$	$V_{CM} = 0\text{V}$ , $R_S = 10\text{k}\Omega$ , 50Ω $\left( \frac{ +I_B  +  -I_B }{2} \right)$	1	+25°C	-	80	nA
			2, 3	+125°C, -55°C	-	150	nA
Input Offset Current	$I_{IO}$	$V_{CM} = 0\text{V}$ , $+R_S = 10\text{k}\Omega$ , $-R_S = 10\text{k}\Omega$	1	+25°C	-75	75	nA
			2, 3	+125°C, -55°C	-135	135	nA
Common Mode Range	+CMR	$V_+ = +4.7\text{V}$ , $V_- = -25.3\text{V}$	1	+25°C	10.3	-	V
			2, 3	+125°C, -55°C	10.3	-	V
	-CMR	$V_+ = +25.3\text{V}$ , $V_- = -4.7\text{V}$	1	+25°C	-	-10.3	V
			2, 3	+125°C, -55°C	-	-10.3	V
Large Signal Voltage Gain	+AVOL	$V_{OUT} = 0\text{V}$ and +10V, $R_L = 2\text{k}\Omega$	4	+25°C	700	-	kV/V
			5, 6	+125°C, -55°C	300	-	kV/V
	-AVOL	$V_{OUT} = 0\text{V}$ and -10V, $R_L = 2\text{k}\Omega$	4	+25°C	700	-	kV/V
			5, 6	+125°C, -55°C	300	-	kV/V
Common Mode Rejection Ratio	+CMRR	$\Delta V_{CM} = +11\text{V}$	1	+25°C	100	-	dB
			2, 3	+125°C, -55°C	100	-	dB
	-CMRR	$\Delta V_{CM} = -11\text{V}$	1	+25°C	100	-	dB
			2, 3	+125°C, -55°C	100	-	dB

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**TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)**

Device Tested at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{SOURCE} = 50\Omega$ ,  $R_{LOAD} = 100k\Omega$ ,  $V_{OUT} = 0V$ , Unless Otherwise Specified.

PARAMETERS	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Output Voltage Swing	+V <sub>OUT1</sub>	$R_L = 2k\Omega$	4	+25°C	11.5	-	V
			5, 6	+125°C, -55°C	11.5	-	V
	-V <sub>OUT1</sub>	$R_L = 2k\Omega$	4	+25°C	-	-11.5	V
			5, 6	+125°C, -55°C	-	-11.5	V
	+V <sub>OUT2</sub>	$R_L = 600\Omega$	4	+25°C	10	-	V
	-V <sub>OUT2</sub>	$R_L = 600\Omega$	4	+25°C	-	-10	V
	+I <sub>OUT</sub>	$V_{OUT} = -10V$	4	+25°C	16.5	-	mA
	-I <sub>OUT</sub>	$V_{OUT} = +10V$	4	+25°C	-	-16.5	mA
Quiescent Power Supply Current	+I <sub>CC</sub>	$V_{OUT} = 0V, I_{OUT} = 0mA$	1	+25°C	-	4	mA
			2, 3	+125°C, -55°C	-	4	mA
	-I <sub>CC</sub>	$V_{OUT} = 0V, I_{OUT} = 0mA$	1	+25°C	-4	-	mA
			2, 3	+125°C, -55°C	-4	-	mA
Power Supply Rejection Ratio	+PSRR	$\Delta V_{SUP} = 14V$	1	+25°C	86	-	dB
		$\Delta V_{SUP} = 13.5V$	2, 3	+125°C, -55°C	86	-	dB
	-PSRR	$\Delta V_{SUP} = 14V$	1	+25°C	86	-	dB
		$\Delta V_{SUP} = 13.5V$	2, 3	+125°C, -55°C	86	-	dB
Offset Voltage Adjustment	+V <sub>IOAdj</sub>	Note 1	1	+25°C	$V_{IO}-1$	-	mV
			2, 3	+125°C, -55°C	$V_{IO}-1$	-	mV
	-V <sub>IOAdj</sub>	Note 1	1	+25°C	$V_{IO}+1$	-	mV
			2, 3	+125°C, -55°C	$V_{IO}+1$	-	mV

NOTE:

1. Offset adjustment range is [ $V_{IO}$  (Measured)  $\pm 1mV$ ] minimum referred to output. This test is for functionality only to assure adjustment through 0V.
2. For differential input voltages greater than 0.7V, the input current must be limited to 25mA to protect the back-to-back input diodes.

**TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS**

Device Tested at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{SOURCE} = 50\Omega$ ,  $R_{LOAD} = 2k\Omega$ ,  $C_{LOAD} = 50pF$ ,  $A_{VCL} = +1V/V$ , Unless Otherwise Specified.

PARAMETERS	SYMBOL	CONDITIONS	GROUP A SUBGROUP	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Slew Rate	+SR	$V_{OUT} = -3V$ to $+3V$	7	+25°C	7	-	V/ $\mu$ s
	-SR	$V_{OUT} = +3V$ to $-3V$	7	+25°C	7	-	V/ $\mu$ s
Rise and Fall Time	t <sub>R</sub>	$V_{OUT} = 0$ to $+200mV$ $10\% \leq T_R \leq 90\%$	7	+25°C	-	150	ns
	t <sub>F</sub>	$V_{OUT} = 0$ to $-200mV$ $10\% \leq T_F \leq 90\%$	7	+25°C	-	150	ns
Overshoot	+OS	$V_{OUT} = 0$ to $+200mV$	7	+25°C	-	40	%
	-OS	$V_{OUT} = 0$ to $-200mV$	7	+25°C	-	40	%

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**TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS**

Device Characterized at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{LOAD} = 2k\Omega$ ,  $C_{LOAD} = 50pF$ ,  $A_V = +1V/V$ , Unless Otherwise Specified.

PARAMETERS	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		
					MIN	MAX	UNITS
Average Offset Voltage Drift	$V_{IO}TC$	$V_{CM} = 0V$	1	-55°C to +125°C	-	1.8	$\mu V/\text{°C}$
Differential Input Resistance	$R_{IN}$	$V_{CM} = 0V$	1	+25°C	0.8	-	$M\Omega$
Low Frequency Peak-to-Peak Noise	$E_{NP-P}$	0.1Hz to 10Hz	1	+25°C	-	0.25	$\mu V_{P-P}$
Input Noise Voltage Density	$E_N$	$R_S = 20\Omega$ , $f_O = 10\text{Hz}$	1	+25°C	-	10.0	$nV/\sqrt{\text{Hz}}$
		$R_S = 20\Omega$ , $f_O = 100\text{Hz}$	1	+25°C	-	5.6	$nV/\sqrt{\text{Hz}}$
		$R_S = 20\Omega$ , $f_O = 1\text{kHz}$	1	+25°C	-	4.5	$nV/\sqrt{\text{Hz}}$
Input Noise Current Density	$I_N$	$R_S = 2M\Omega$ , $f_O = 10\text{Hz}$	1	+25°C	-	4.0	$pA/\sqrt{\text{Hz}}$
		$R_S = 2M\Omega$ , $f_O = 100\text{Hz}$	1	+25°C	-	2.3	$pA/\sqrt{\text{Hz}}$
		$R_S = 2M\Omega$ , $f_O = 1\text{kHz}$	1	+25°C	-	0.6	$pA/\sqrt{\text{Hz}}$
Unity Gain Bandwidth	UGBW	$V_O = 100mV$	1	+25°C	5	-	MHz
Full Power Bandwidth	FPBW	$V_{PEAK} = 10V$	1, 2	+25°C	111	-	kHz
Minimum Closed Loop Stable Gain	CLSG	$R_L = 2k\Omega$ , $C_L = 50pF$	1	-55°C to +125°C	$\pm 1$	-	$V/V$
Settling Time	$t_S$	To 0.1% for a 10V Step	1	+25°C	-	2	$\mu s$
Output Resistance	$R_{OUT}$	Open Loop	1	+25°C	-	100	$\Omega$
Quiescent Power Consumption	PC	$V_{OUT} = 0V$ , $I_{OUT} = 0mA$	1, 3	-55°C to +125°C	-	120	mW

NOTES:

1. Parameters listed in Table 3 are controlled via design or process parameters and are not directly tested at final production. These parameters are lab characterized upon initial design release, or upon design changes. These parameters are guaranteed by characterization based upon data from multiple production runs which reflect lot to lot and within lot variation.
2. Full Power Bandwidth guarantee based on Slew Rate measurement using  $FPBW = \text{Slew Rate}/(2\pi V_{PEAK})$ .
3. Quiescent Power Consumption based upon Quiescent Supply Current test maximum. (No load on output.)

**TABLE 4. ELECTRICAL TEST REQUIREMENTS**

MIL-STD-883 TEST REQUIREMENTS	SUBGROUPS (SEE TABLES 1 AND 2) (NOTE 2)
Interim Electrical Parameters (Pre Burn-In)	1
Final Electrical Test Parameters	1 (Note 1), 2, 3, 4, 5, 6, 7
Group A Test Requirements	1, 2, 3, 4, 5, 6, 7
Groups C and D Endpoints	1

NOTES:

1. PDA applies to Subgroup 1 only.
2. The Subgroup assignments of the parameters in these tables were patterned after Mil-M-38510/135, with the exception of  $V_{IO}$ , which is Subgroups 1, 2, 3.

**Die Characteristics****DIE DIMENSIONS:**

104 x 65 x 19 mils  $\pm$  1 mils  
 2650 x 1650 x 483 $\mu$ m  $\pm$  25.4 $\mu$ m

**METALLIZATION:**

Type: Al, 1% Cu  
 Thickness: 16k $\text{\AA}$   $\pm$  2k $\text{\AA}$

**GLASSIVATION:**

Type: Nitride (Si<sub>3</sub>N<sub>4</sub>) over Silox (SiO<sub>2</sub>, 5% Phos.)  
 Silox Thickness: 12k $\text{\AA}$   $\pm$  2k $\text{\AA}$   
 Nitride Thickness: 3.5k $\text{\AA}$   $\pm$  1.5k $\text{\AA}$

**WORST CASE CURRENT DENSITY:**

$3.6 \times 10^5$  A/cm<sup>2</sup>

This device meets Glassivation Integrity Test Requirement  
 per MIL-STD-883 Method 2021 and MIL-I-38535 Paragraph 30.5.5.4.

**SUBSTRATE POTENTIAL (Powered Up): V-****TRANSISTOR COUNT:** 63**PROCESS:** Bipolar Dielectric Isolation***Metallization Mask Layout***

HA-5127/883

